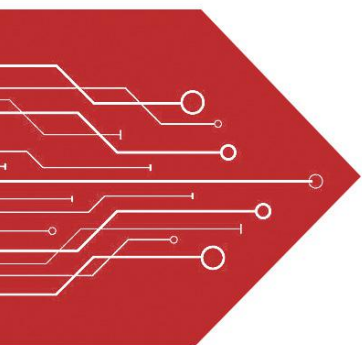


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



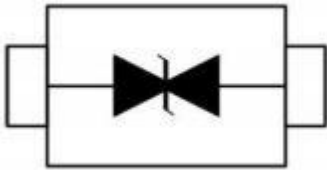
GDT



PLED

Product data sheet

PIN CONFIGURATION



SOD-323

FEATURES

- IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (Contact)
 $\pm 30\text{kV}$ (Air)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ 350 Watts Peak Pulse Power per (tp=8/20μs)
- ✧ Protects one I/O line (bidirectional)
- ✧ Low clamping voltage
- ✧ Working voltages:
3.3V, 5V, 8V, 12V, 15V, 18V, 20V, 24V, 36V
- ✧ Low leakage current

MACHANICAL DATA

- ✧ SOD-323 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Packaging: Tape and Reel
- ✧ High temperature soldering guaranteed:
260°C/10s
- ✧ Reel size: 7 inch
- ✧ MSL 1

APPLICATIONS

- ✧ Cell Phone Handsets and Accessories
- ✧ Microprocessor based equipment
- ✧ Personal Digital Assistants (PDA's)
- ✧ Notebooks, Desktops, and Servers
- ✧ Portable Instrumentation
- ✧ Networking and Telecom
- ✧ Serial and Parallel Ports.
- ✧ Peripherals

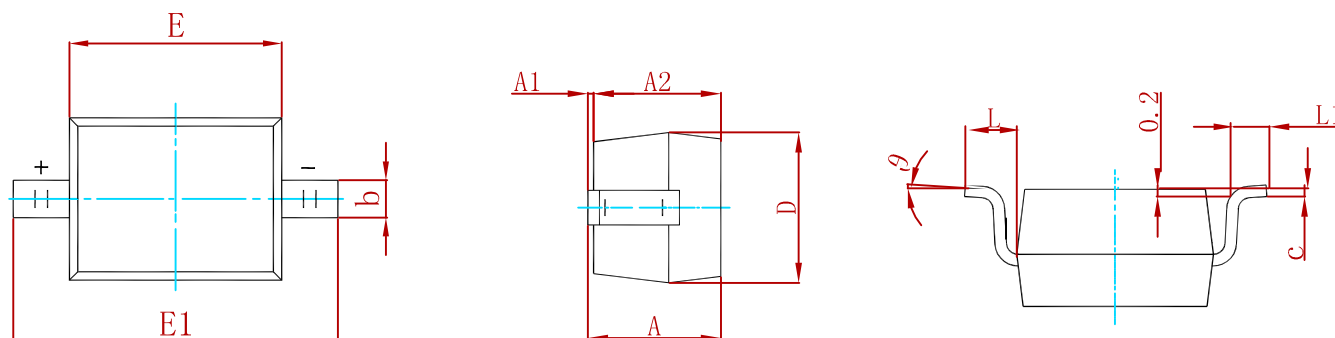
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V _{ESD}	ESD per IEC 61000-4-2 (Contact)	±30	kV
	ESD per IEC 61000-4-2 (Air)	±30	
P _{PP}	Peak Pulse Power (8/20μs)	350	W
T _{OPT}	Operating Temperature	-55/+150	°C
T _{STG}	Storage Temperature	-55/+150	°C
T _L	Lead Soldering Temperature	260 (10 sec.)	°C

ELECTRICAL CHARACTERISTICS (T_{amb}=25°C)

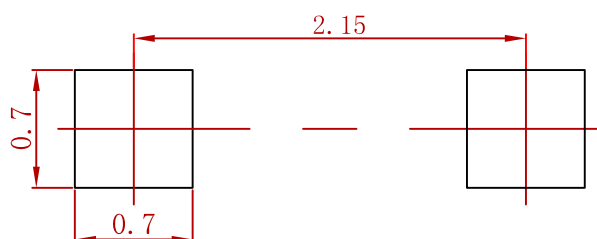
P/N	MARK	V _{RWM} (V) max	V _B (V) min	I _r (mA)	V _{C@1A} (V) (max.)	V _C (V) (max.) (@A)		I _R (μA) (max.)	C _T (pF) (max.)
PSD03C	2A	3.3	4.0	1	7.5	16.0	20	40	450
PSD05C	2B	5.0	6.0	1	9.8	18.0	17	10	200
PSD08C	2C	8.0	8.5	1	13.4	24.0	15	2	120
PSD12C	2D	12.0	13.3	1	19.0	32.0	11	1	75
PSD15C	2J	15.0	16.7	1	24.0	38.0	10	1	68
PSD18C	2K	18.0	20.0	1	29.0	45.0	9	1	57
PSD20C	2L	20.0	22.3	1	35.0	50.0	8	1	52
PSD24C	2H	24.0	26.7	1	43.0	52.0	7	1	50
PSD36C	2N	36.0	40.0	1	60.0	75.0	4.5	1	35

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PSDXXC	SOD-323	3000

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